

R2A20101BM/NP

Monolithic Synchronous Step-Down DC/DC Converter

REJ03D0790-0300

Rev.3.00

May 14, 2008

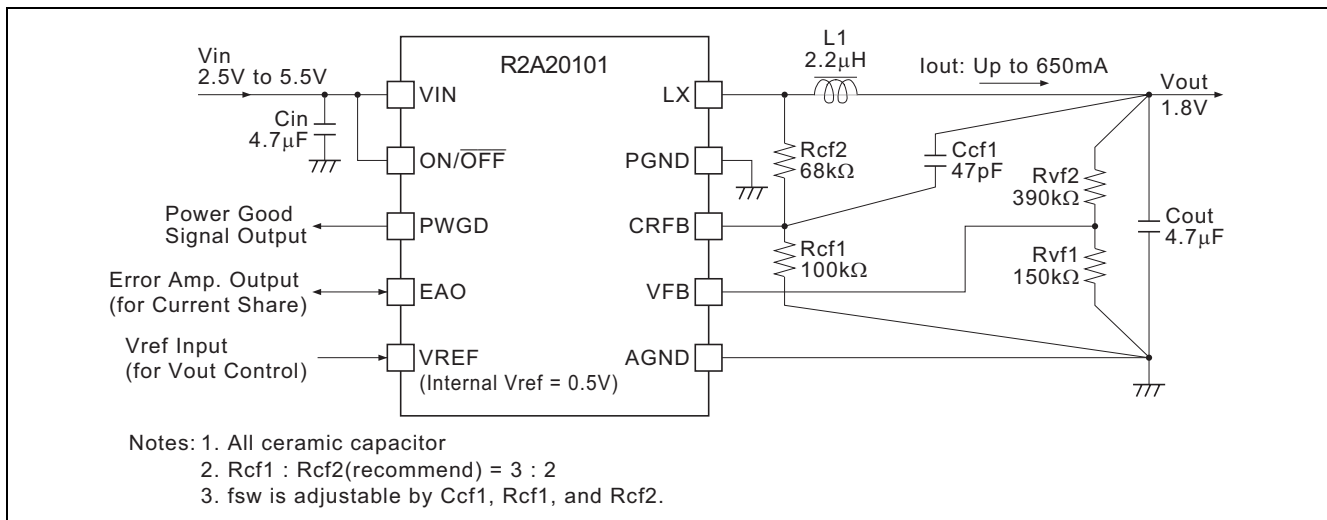
Features

- Built-in low Ron power MOS FETs
Pch Ron = 0.30 Ω (Typ), Nch Ron = 0.14 Ω (Typ)
- High switching frequency: 2 MHz (Max)
- Output current: 650 mA (Max)
- Output ON/OFF control
- Vout control
- Power good monitor
- Current share for redundant power supply operation
- Vout = 0.5 V to (VIN - 0.5) V

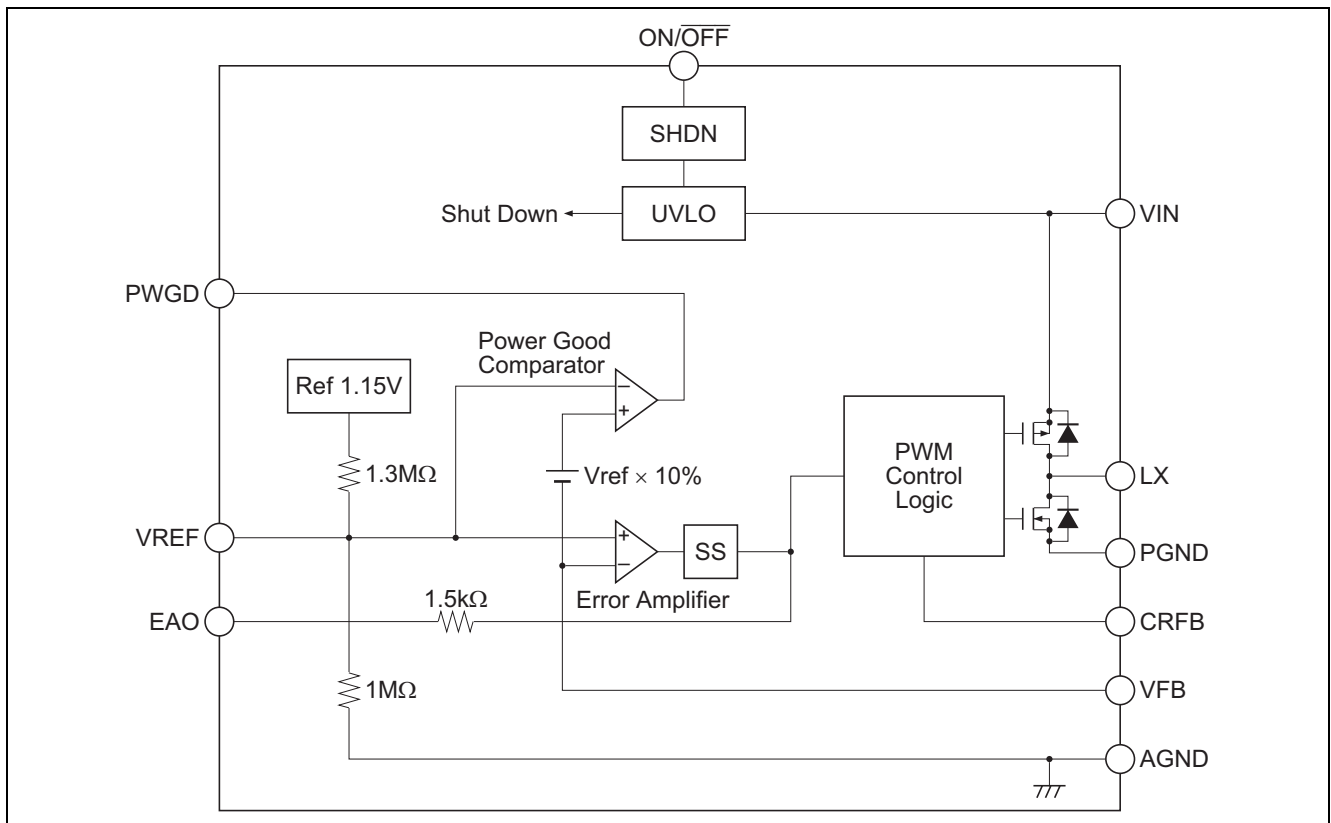
Application

- POL (Point of Load) power supplies
- Power supply for microcomputer systems
MCU-Core, I/O, Memory (DDR, SRAM, FLASH, HDD, etc.), FPGA, DSP, Graphic Processor
- Battery powered equipment systems
Cellular phone (CDMA power amplifier, MCU, DSP, ASIC), PDA, Digital camera, Portable game, Handy terminal

Operating Circuit Example



Block Diagram



Absolute Maximum Ratings

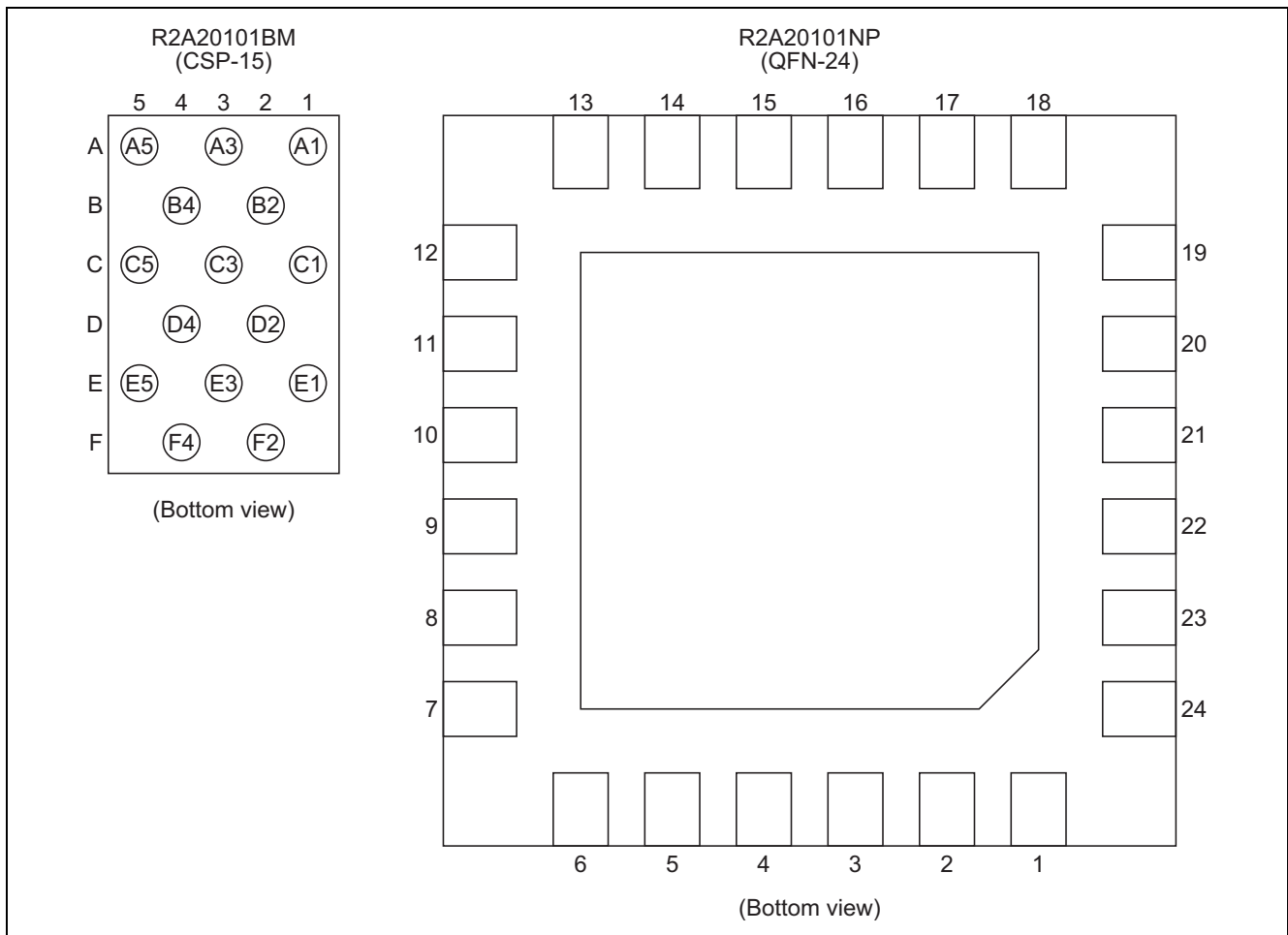
(Ta = 25°C)

Item	Symbol	Ratings	Unit	Note
Power supply voltage	V _{IN}	6	V	1
ON/OFF, PWGD, EAO, VREF, LX, CRFB, VFB terminal voltage	V _{MAX}	-0.3 to (V _{IN} + 0.3)	V	1
PGND terminal voltage	V _{PGND}	-0.3 to +0.3	V	1
Operating ambient temperature	T _{opr} (Ta)	-40 to +85	°C	
Junction temperature 1	T _{jmax1}	+125	°C	
Junction temperature 2	T _{jmax2}	+150	°C	2
Storage temperature	T _{stg}	-55 to +150	°C	

Notes: 1. Rated voltages are with reference to the AGND pin.

2. Operation by T_{jmax2} is made within 24 hours through life.

Pin Arrangement



Pin Description

Pin No.		Pin Name	Pin Function
R2A20101BM (CSP-15)	R2A20101NP (QFN-24)		
A1, A3, A5	15, 16, 17	PGND	Power ground
B2, B4	11, 20	LX	Inductor connection node
C1, C3, C5	10, 21	VIN	Power supply voltage input
D4	22	ON/OFF	Output on/off control input
D2	9	CRFB	CR feedback input
E5	23	PWGD	Power good monitor output
E1	8	VFB	Feedback voltage input
F4	2	EAO	Error amplifier output (for current share)
E3	5	VREF	Vout control voltage input
F2	4	AGND	Analog ground (IC chip ground voltage)

Note: Please apply solder to pins 1, 3, 6, 7, 12, 13, 14, 18, 19, and 24 even though they are NC pins. Solder on the underside pads improves heat-radiation characteristics.

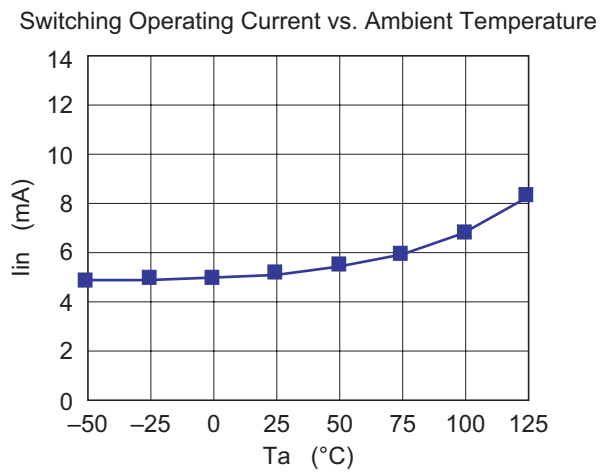
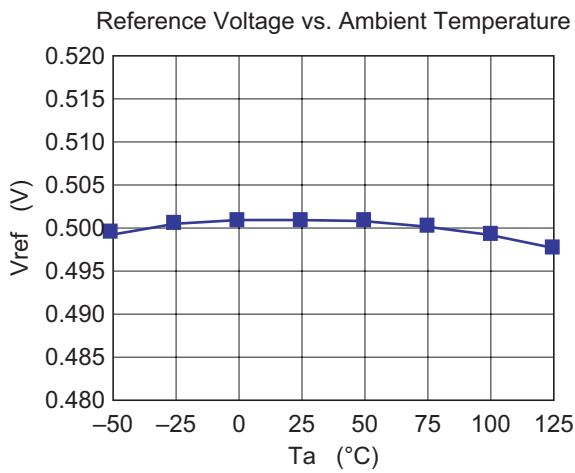
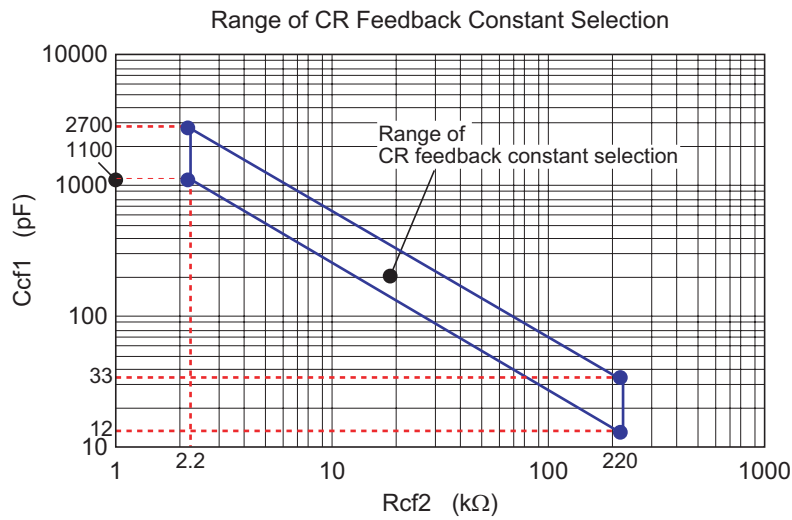
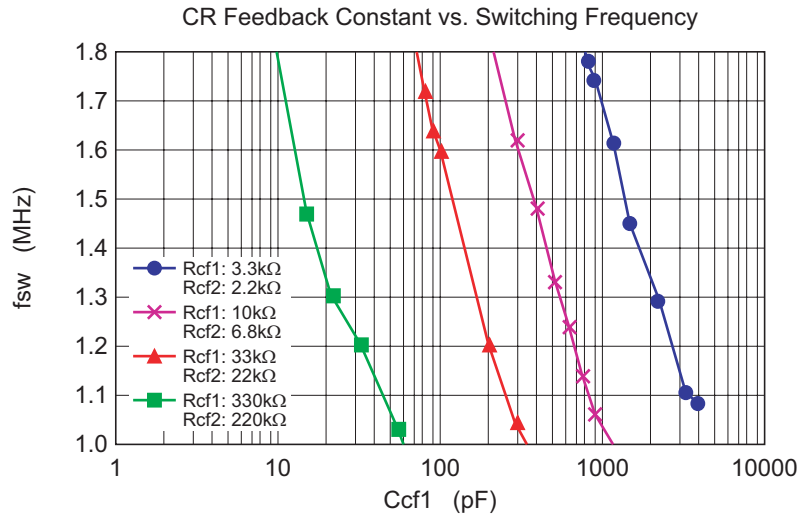
Electrical Characteristics

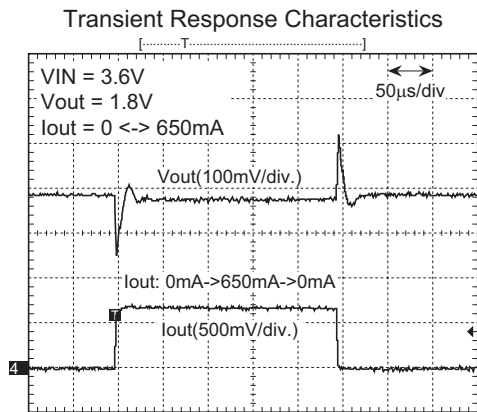
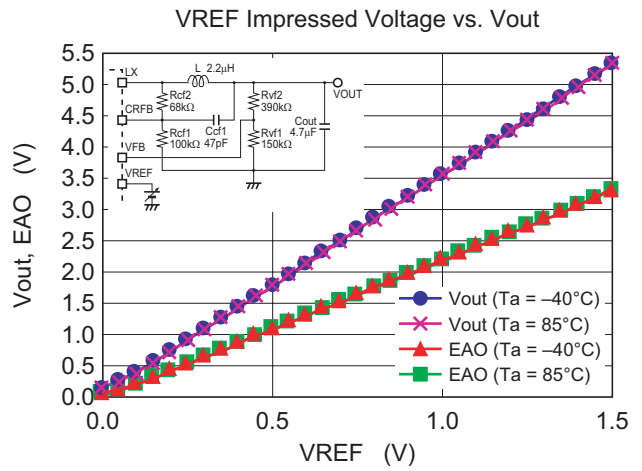
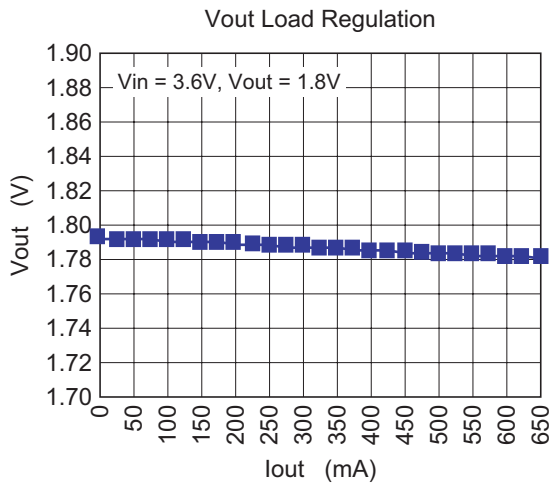
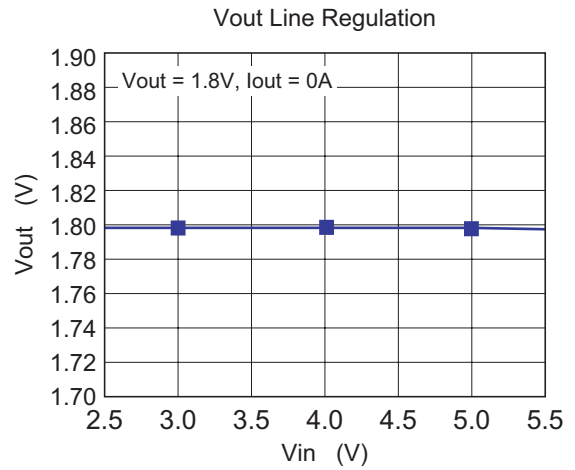
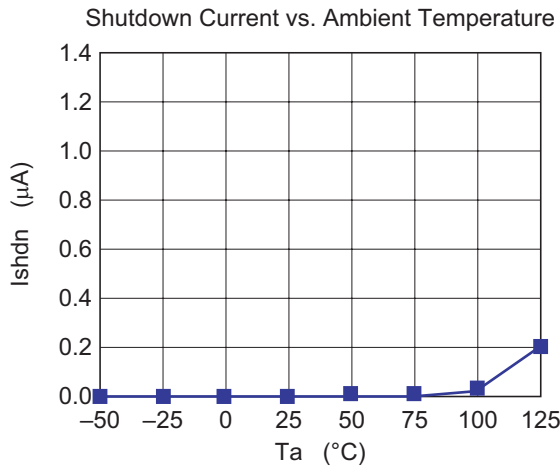
(Ta = 25°C, Vin = 3.6 V, ON/OFF = Vin, unless otherwise specified.)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Input voltage range	Vin	2.5	—	5.5	V	
UVL threshold high	VuVl-Hi	2.0	2.3	2.5	V	VFB = CRFB = GND, Vin = rising
UVL hysteresis	VuVl-Hys	0.15	0.22	0.29	V	
Quiescent supply current	I _{ss}	20	45	80	μA	
Shutdown supply current	I _{shdn}	—	0.0	1.0	μA	ON/OFF = 0V
Reference voltage	V _{ref}	0.485	0.500	0.515	V	
V _{ref} line regulation	dV _{ref} /dV _{in}	(-0.4)	0.1	(0)	%/V	Vin = 2.5 to 5.5V
V _{ref} temperature stability	dV _{ref} /dT _a	—	(±100)	—	ppm/°C	T _a = -40 to +85°C
VREF sink current	I _{vref-sink}	1.3	3.7	8.0	μA	V _{ref} = 2.5V
VREF source current	I _{vref-source}	0.3	0.9	2.0	μA	V _{ref} = 0V
VFB leakage current	I _{leak-VFB}	-1	0	+1	μA	VFB = 1/2 × Vin
Pch FET on resistance	R _{on-Pch}	—	0.30	0.50	Ω	VFB = CRFB = 0V, ILX = -100mA
Nch FET on resistance	R _{on-Nch}	—	0.14	0.25	Ω	VFB = CRFB = Vin, ILX = 100mA
Pch FET leakage current	I _{leak-Pch}	—	—	1.0	μA	ON/OFF = 0V, LX = 0V
Nch FET leakage current	I _{leak-Nch}	—	—	1.0	μA	ON/OFF = 0V, LX = Vin
Peak current limit	I _{peak-Limit}	0.7	—	—	A	
ON/OFF threshold high	V _{on/off-Hi}	1.0	1.45	1.85	V	ON/OFF = rising
ON/OFF threshold low	V _{on/off-Lo}	0.75	1.24	1.65	V	ON/OFF = falling
ON/OFF leakage current	I _{leak-on/off}	-1	0	+1	μA	ON/OFF = Vin
ON/OFF input current	I _{input-on/off}	—	1.4	5	μA	ON/OFF = 0.9V
Switching frequency	f _{sw}	Adjustable by external Ccf1, Rcf1, Rcf2			Hz	
Soft start time	t _{ss}	56 × Rcf1/(Rcf1 + Rcf2) × V _{out}			μs	
Power good threshold	V _{th-PGood}	(-15)	-10	(-5)	%	V _{ref} = 0.5V
Power good VOL	I _{pg-VOL}	20	—	—	μA	PWGD = 0.2V, VFB = 0V
Power good VOH	I _{pg-VOH}	-10	—	—	μA	PWGD = 3.4V, VFB = 0.5V
Output voltage load regulation	dV _{out} /dI _{out}	—	±0.7	—	%/A	L = 2.2μH, V _{out} = 1.8V, I _{out} = 0 to 650mA

Note: () is design spec.

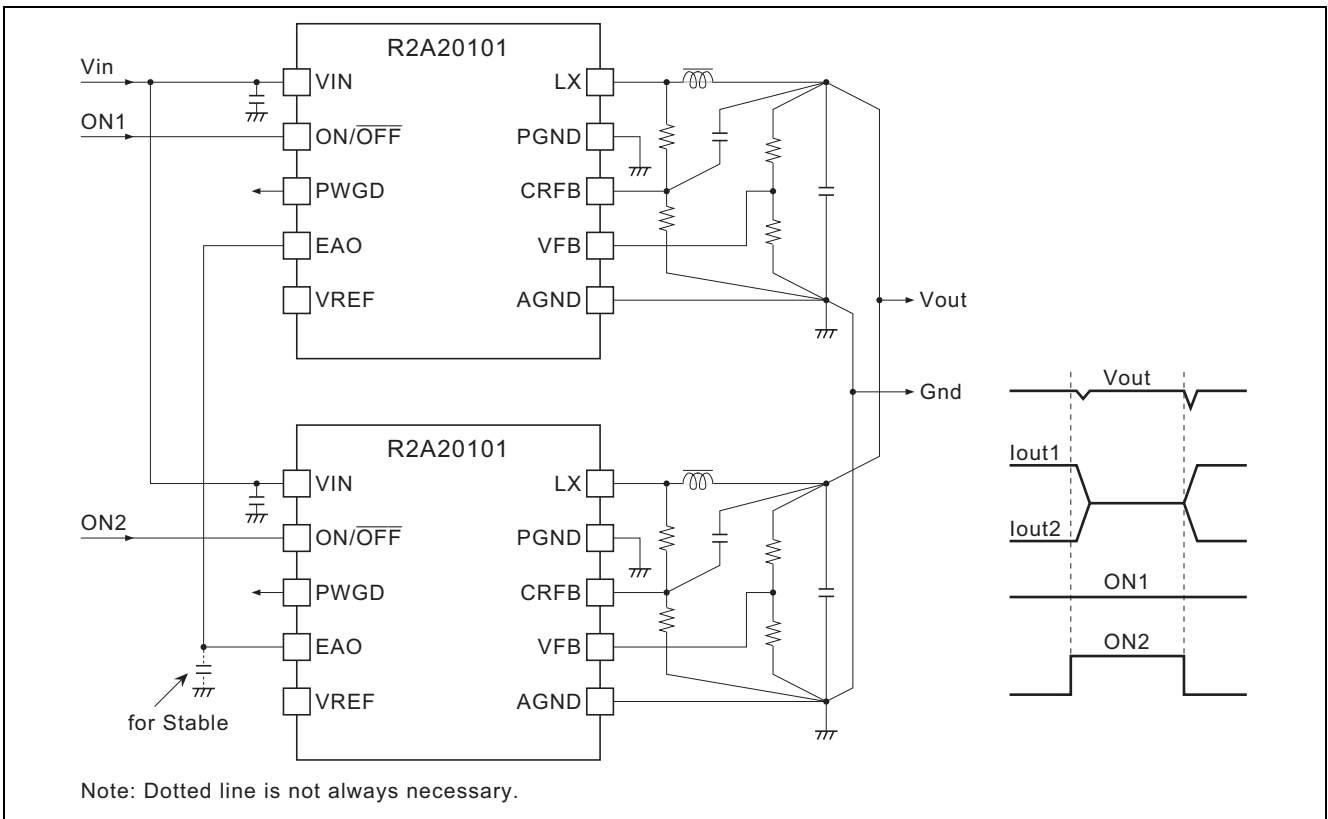
Main Characteristics



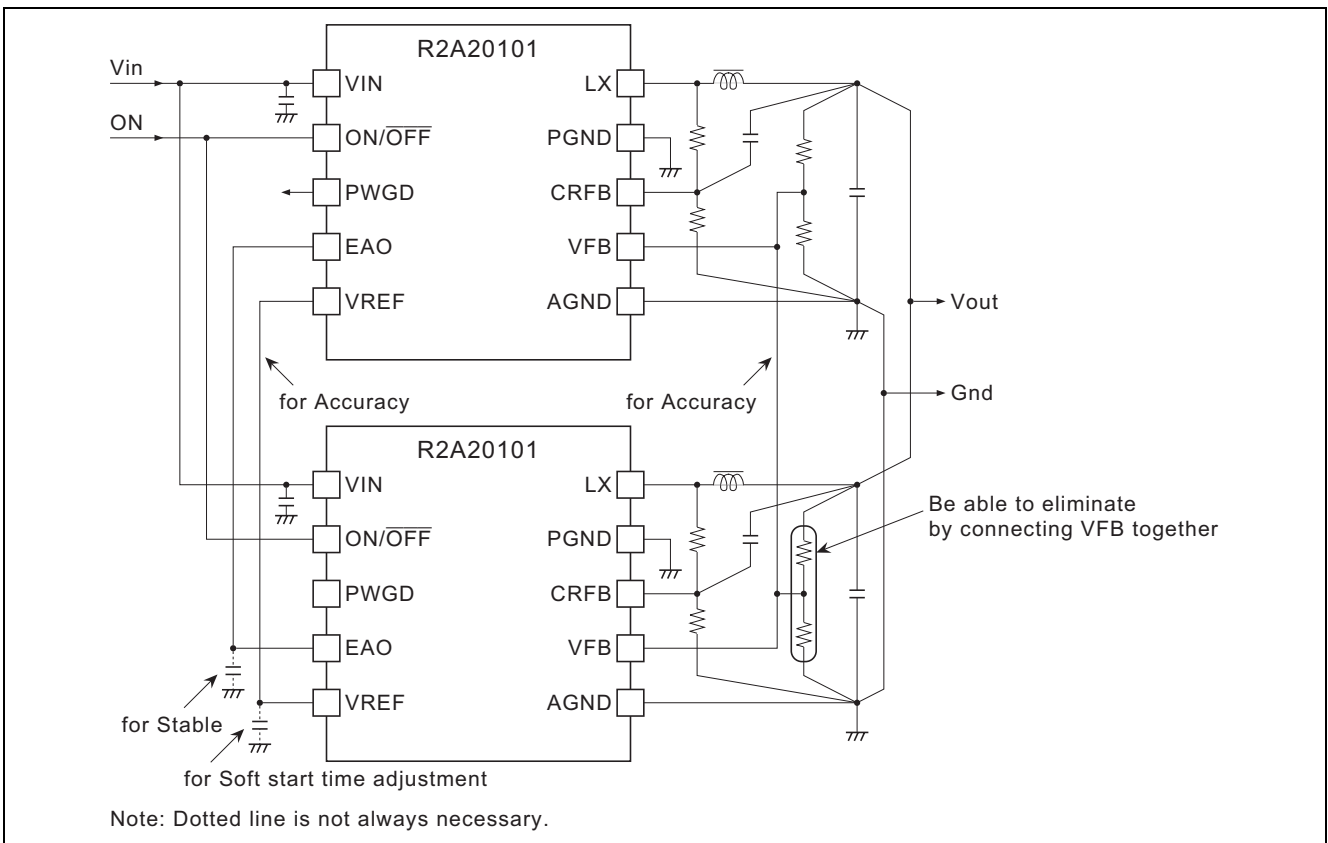


Application Circuit Example

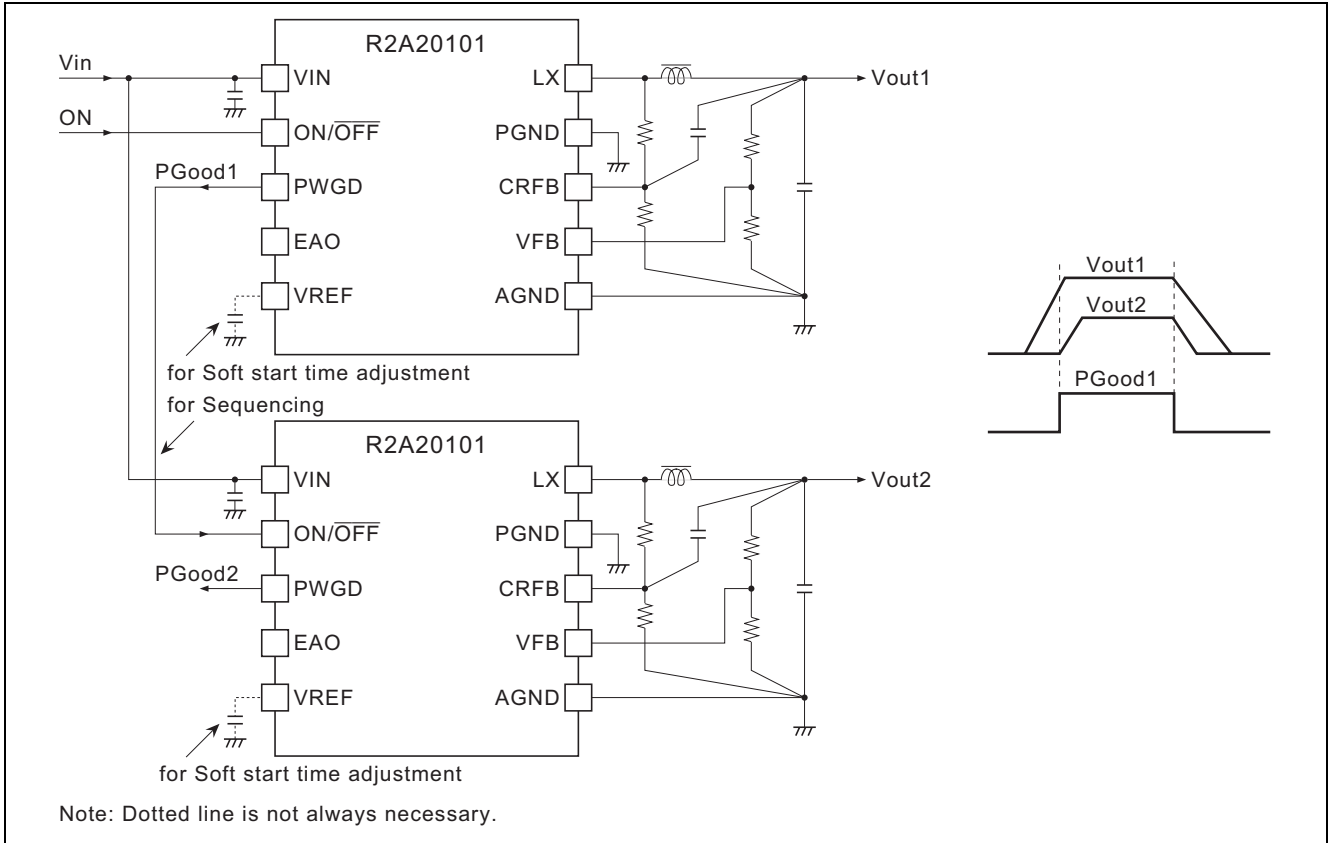
1. Current Share 1 (Redundant, Hot Swap type)



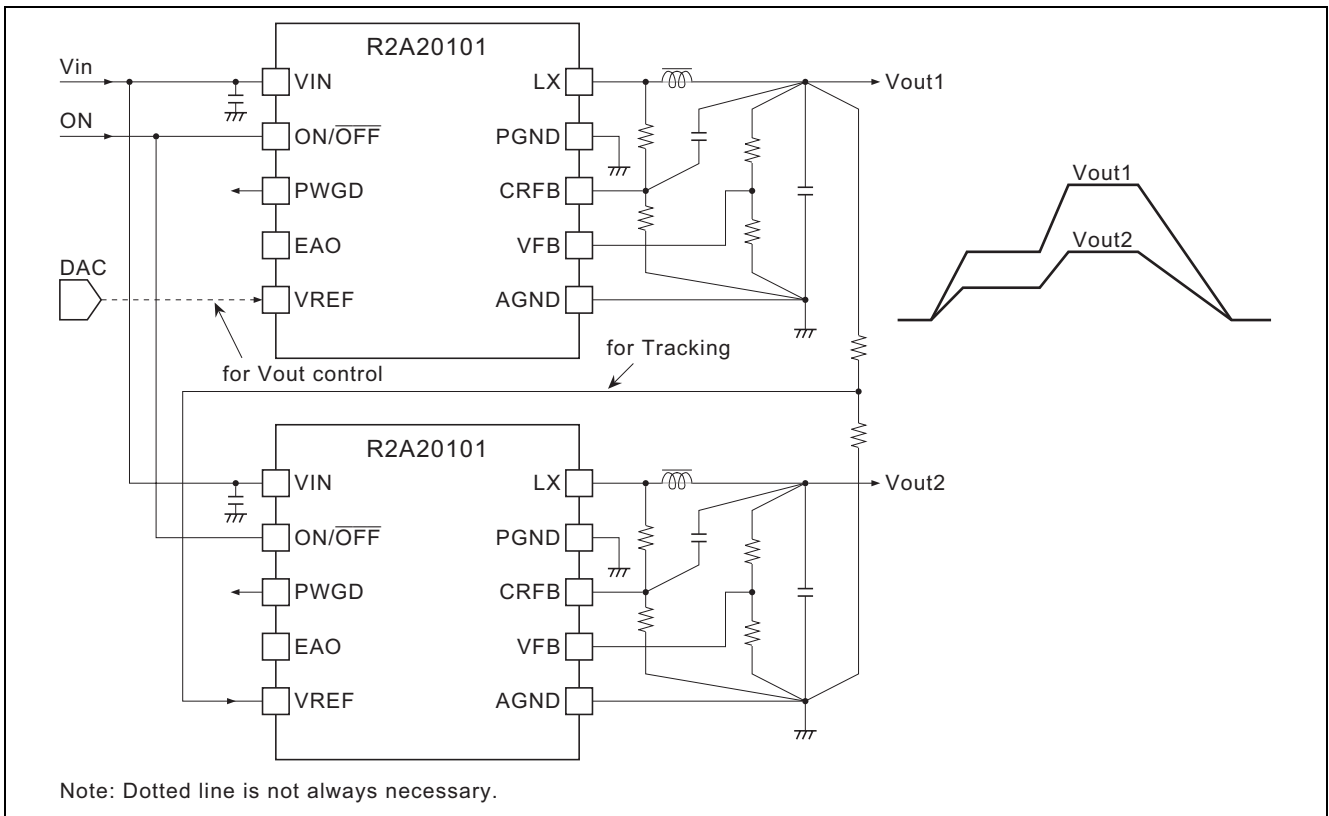
2. Current Share 2 (Accuracy type)



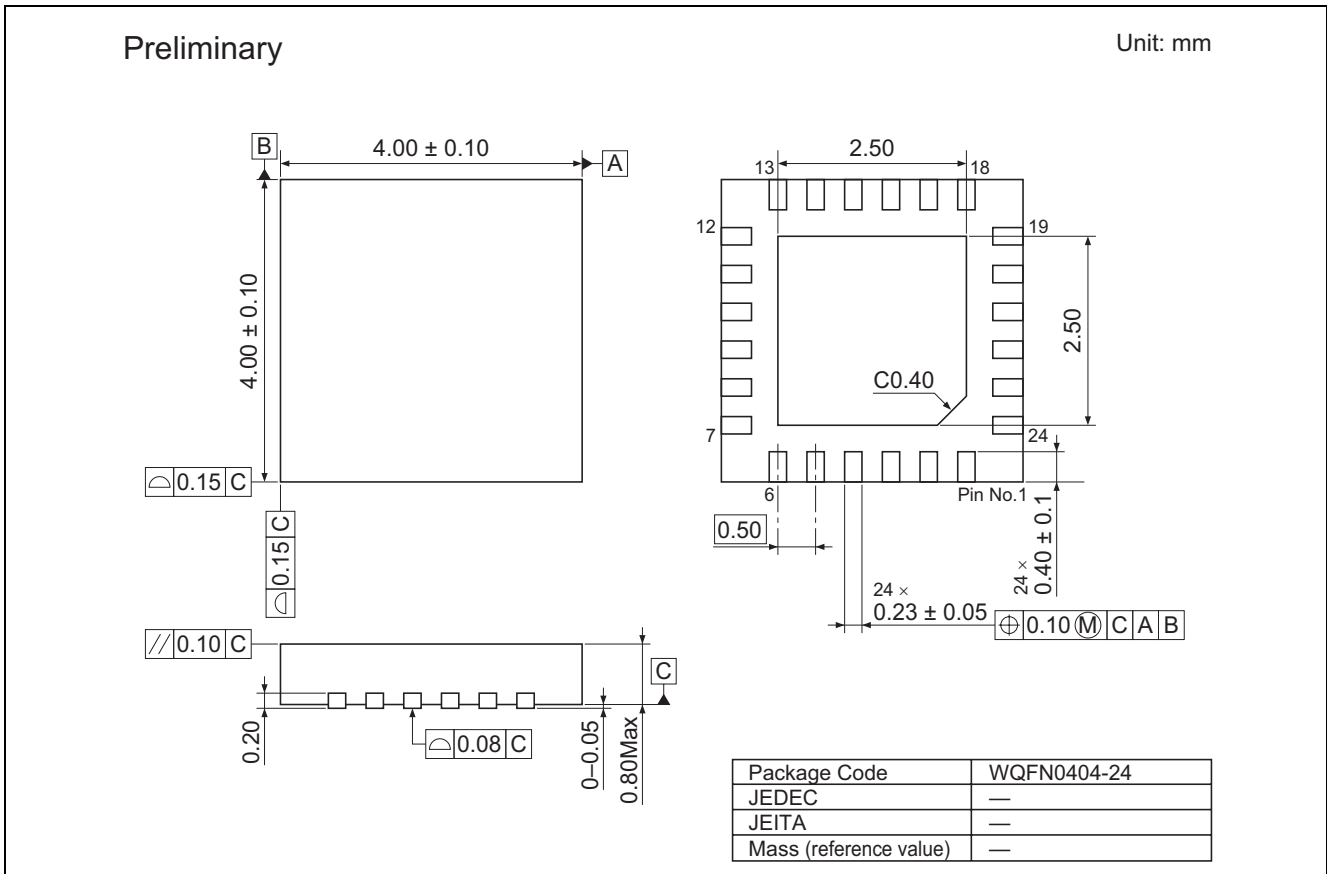
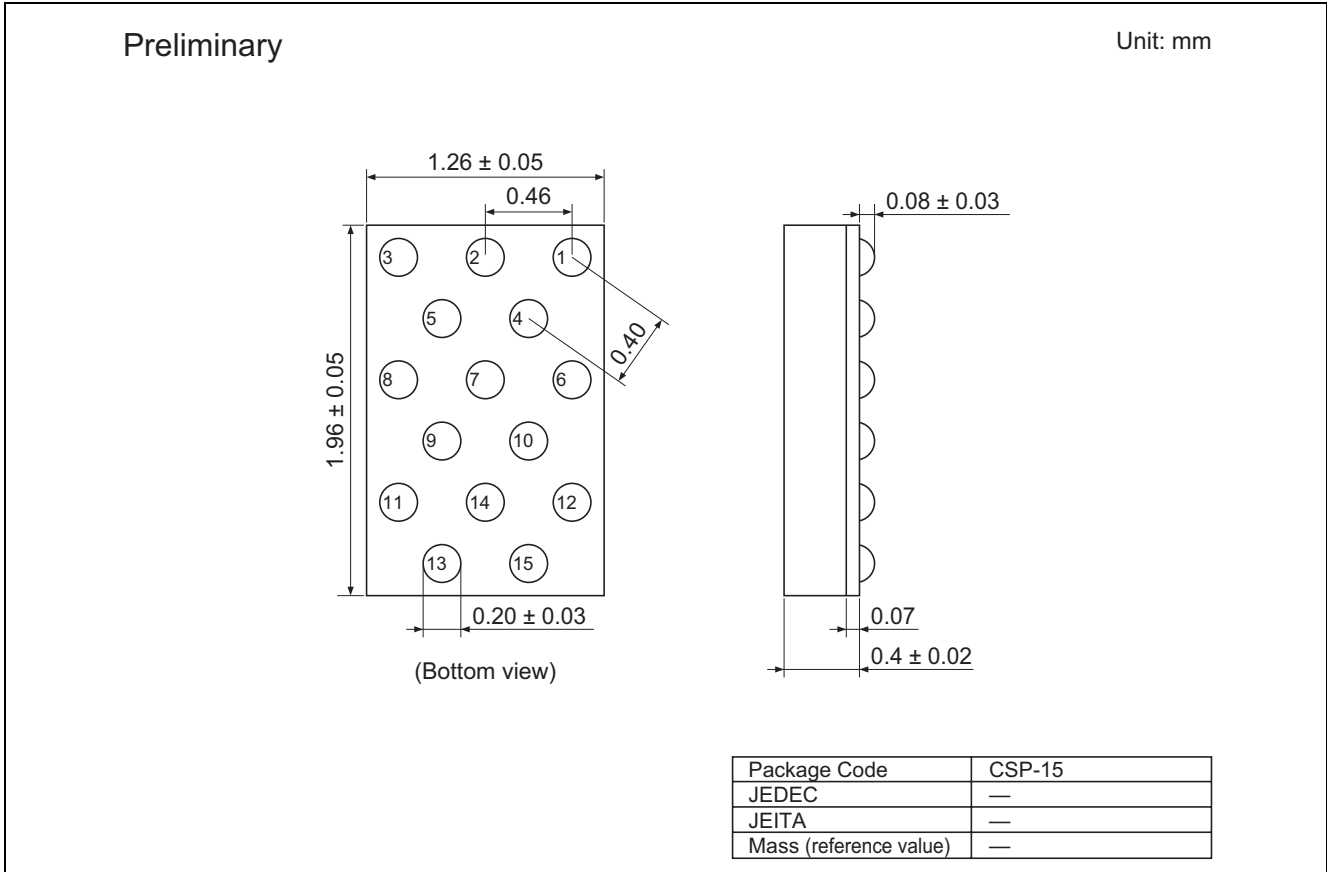
3. Sequential Start-up



4. Tracking



Package Dimensions



Notes:

1. This document is provided for reference purposes only so that Renesas customers may select the appropriate Renesas products for their use. Renesas neither makes warranties or representations with respect to the accuracy or completeness of the information contained in this document nor grants any license to any intellectual property rights or any other rights of Renesas or any third party with respect to the information in this document.
2. Renesas shall have no liability for damages or infringement of any intellectual property or other rights arising out of the use of any information in this document, including, but not limited to, product data, diagrams, charts, programs, algorithms, and application circuit examples.
3. You should not use the products or the technology described in this document for the purpose of military applications such as the development of weapons of mass destruction or for the purpose of any other military use. When exporting the products or technology described herein, you should follow the applicable export control laws and regulations, and procedures required by such laws and regulations.
4. All information included in this document such as product data, diagrams, charts, programs, algorithms, and application circuit examples, is current as of the date this document is issued. Such information, however, is subject to change without any prior notice. Before purchasing or using any Renesas products listed in this document, please confirm the latest product information with a Renesas sales office. Also, please pay regular and careful attention to additional and different information to be disclosed by Renesas such as that disclosed through our website. (<http://www.renesas.com>)
5. Renesas has used reasonable care in compiling the information included in this document, but Renesas assumes no liability whatsoever for any damages incurred as a result of errors or omissions in the information included in this document.
6. When using or otherwise relying on the information in this document, you should evaluate the information in light of the total system before deciding about the applicability of such information to the intended application. Renesas makes no representations, warranties or guarantees regarding the suitability of its products for any particular application and specifically disclaims any liability arising out of the application and use of the information in this document or Renesas products.
7. With the exception of products specified by Renesas as suitable for automobile applications, Renesas products are not designed, manufactured or tested for applications or otherwise in systems the failure or malfunction of which may cause a direct threat to human life or create a risk of human injury or which require especially high quality and reliability such as safety systems, or equipment or systems for transportation and traffic, healthcare, combustion control, aerospace and aeronautics, nuclear power, or undersea communication transmission. If you are considering the use of our products for such purposes, please contact a Renesas sales office beforehand. Renesas shall have no liability for damages arising out of the uses set forth above.
8. Notwithstanding the preceding paragraph, you should not use Renesas products for the purposes listed below:
 - (1) artificial life support devices or systems
 - (2) surgical implantations
 - (3) healthcare intervention (e.g., excision, administration of medication, etc.)
 - (4) any other purposes that pose a direct threat to human lifeRenesas shall have no liability for damages arising out of the uses set forth in the above and purchasers who elect to use Renesas products in any of the foregoing applications shall indemnify and hold harmless Renesas Technology Corp., its affiliated companies and their officers, directors, and employees against any and all damages arising out of such applications.
9. You should use the products described herein within the range specified by Renesas, especially with respect to the maximum rating, operating supply voltage range, movement power voltage range, heat radiation characteristics, installation and other product characteristics. Renesas shall have no liability for malfunctions or damages arising out of the use of Renesas products beyond such specified ranges.
10. Although Renesas endeavors to improve the quality and reliability of its products, IC products have specific characteristics such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Please be sure to implement safety measures to guard against the possibility of physical injury, and injury or damage caused by fire in the event of the failure of a Renesas product, such as safety design for hardware and software including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other applicable measures. Among others, since the evaluation of microcomputer software alone is very difficult, please evaluate the safety of the final products or system manufactured by you.
11. In case Renesas products listed in this document are detached from the products to which the Renesas products are attached or affixed, the risk of accident such as swallowing by infants and small children is very high. You should implement safety measures so that Renesas products may not be easily detached from your products. Renesas shall have no liability for damages arising out of such detachment.
12. This document may not be reproduced or duplicated, in any form, in whole or in part, without prior written approval from Renesas.
13. Please contact a Renesas sales office if you have any questions regarding the information contained in this document, Renesas semiconductor products, or if you have any other inquiries.



RENESAS SALES OFFICES

<http://www.renesas.com>

Refer to "<http://www.renesas.com/en/network>" for the latest and detailed information.

Renesas Technology America, Inc.
450 Holger Way, San Jose, CA 95134-1368, U.S.A
Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

Renesas Technology Europe Limited
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.
Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

Renesas Technology (Shanghai) Co., Ltd.
Unit 204, 205, AZIA Center, No.1233 Lujiazui Ring Rd, Pudong District, Shanghai, China 200120
Tel: <86> (21) 5877-1818, Fax: <86> (21) 6887-7858/7898

Renesas Technology Hong Kong Ltd.
7th Floor, North Tower, World Finance Centre, Harbour City, Canton Road, Tsimshatsui, Kowloon, Hong Kong
Tel: <852> 2265-6688, Fax: <852> 2377-3473

Renesas Technology Taiwan Co., Ltd.
10th Floor, No.99, Fushing North Road, Taipei, Taiwan
Tel: <886> (2) 2715-2888, Fax: <886> (2) 3518-3399

Renesas Technology Singapore Pte. Ltd.
1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632
Tel: <65> 6213-0200, Fax: <65> 6278-8001

Renesas Technology Korea Co., Ltd.
Kukje Center Bldg. 18th Fl., 191, 2-ka, Hangang-ro, Yongsan-ku, Seoul 140-702, Korea
Tel: <82> (2) 796-3115, Fax: <82> (2) 796-2145

Renesas Technology Malaysia Sdn. Bhd
Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: <603> 7955-9390, Fax: <603> 7955-9510